



**REVISION RECORD**

REVISION	REVISION DATE	PAGE	CONTENTS
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※ **CONTENTS**

1. GENERAL SPECIFICATIONS
2. PIN ASSIGNMENT
3. OPERATING SPECIFICATIONS
4. OPTICAL SPECIFICATIONS
5. RELIABILITY TEST
6. PRECAUTION FOR USING LCM
7. MECHANICAL DRAWING
8. PACKAGE DRAWING
9. INSPECTION SPECIFICATION

# ATMD210M1B (AZ DISPLAYS) TFT MODULE SPEC VER1.0

## 1. GENERAL SPECIFICATIONS

Item	Specification	Remark
1. LCD size	2.1 inch(Diagonal)	
2. Driver element	a-Si TFT active matrix	
3. Resolution	480x(RGB)x480	
4. Display mode	Normally Black, IPS, Transmissive	
5. Dot pitch (W*H)	0.037mm(W) x 0.111mm(H)	
6. Pixel pitch(W*H)	0.111mm(W) x 0.111mm(H)	
7. Active area(W*H)	53.28mm(W) x 53.28mm(H)	
8. Module size (W*H)	56.18mm(W) x 59.71mm(H) x2.22mm(D)	Note 1
9. Surface treatment	Anti-glare	
10. Color arrangement	RGB-stripe	
11. Color	16.7M	
12. Viewing angle (L/R/T/B)	85/85/85/85(Typ.)	
13. Interface	2 lane MIPI	
14. LCD controller	ST7701S	
15. LCM brightness	600cd/m2(Typ.)	
16. Backlight driving condition	80mA @6.0V	
17. Touch panel	N.A.	
18. Touch controller	N.A.	
19. Operation temperature	-20~70 °C	
20. Weight	T.B.D g(Typ.)	
21. RoHS	RoHS compliant	

**Note 1: Please refer to mechanical drawing.**

## 2. PIN ASSIGNMENT

### TFT LCD Panel Driving Section

Pin No.	Symbol	Function	Level	Note
1	GND	Ground	P	
2	MIPI-D0P	MIPI-DSI data Lane 0 positive-end input/output pin	I	
3	MIPI-D0N	MIPI-DSI data Lane 0 negative-end input/output pin	I	
4	GND	Ground	P	
5	MIPI-D1P	MIPI-DSI data Lane 1 positive-end input/output pin	I	
6	MIPI-D1N	MIPI-DSI data Lane 1 negative-end input/output pin	I	
7	GND	Ground	P	
8	MIPI-CLKP	MIPI-DSI clock Lane positive-end input pin	I	
9	MIPI-CLKN	MIPI-DSI clock Lane negative-end input pin	I	
10	GND	Ground	P	
11	NC	No connection	-	
12	NC	No connection	-	
13	NC	No connection	-	
14	NC	No connection	-	
15	NC	No connection	-	
16~17	NC	No connection	-	
18~19	IOVCC	I/O power supply	P	
20~23	NC	No connection	-	
24	RST	Reset signal	I	
25~26	NC	No connection	-	
27	GND	Ground	P	
28~29	LEDK	Power for LED backlight(Cathode)	P	
30	GND	Ground	P	
31	NC	No connection	-	
32~33	GND	Ground	P	
34	NC	No connection	-	
35~36	LEDA	Power for LED backlight(Anode)	P	
37	GND	Ground	P	
38~39	VDD	Power supply	P	
40	NC	No connection	-	

**I: input, O: output, P: Power**

### 3. Operating Specification

#### 3.1.1 ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Values		Unit	Remark
		Min.	Max.		
Power Voltage	VDD	-0.3	4.6	V	
I/O Power Voltage	IOVCC	-0.3	4.6	V	
Operation Temperature	T <sub>OP</sub>	-20	70	°C	
Storage Temperature	T <sub>ST</sub>	-30	80	°C	
LED Reverse Voltage	V <sub>R</sub>	-	1.2	V	Each LED Note 2
LED Forward Current	I <sub>F</sub>		25	mA	Each LED

**Note 1:** The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

**Note 2:** V<sub>R</sub> Conditions: Zener Diode 20mA

#### 3.1.2 Typical Operation Conditions

Item	Symbol	Values			Unit	Remark
		Min.	Typ.	Max.		
Logis Power Voltage	VDD	2.5	2.8	3.3	V	Note 1
I/O Power Voltage	IOVCC	1.65	2.8	3.3	V	
Input Logic High Voltage	V <sub>IH</sub>	0.7IOVCC	--	IOVCC	V	
Input Logic Low Voltage	V <sub>IL</sub>	0	--	0.3IOVCC	V	

**Note 1:** V<sub>DD</sub> setting should match the signals output voltage of customer's system board, IOVCC ≤ VDD

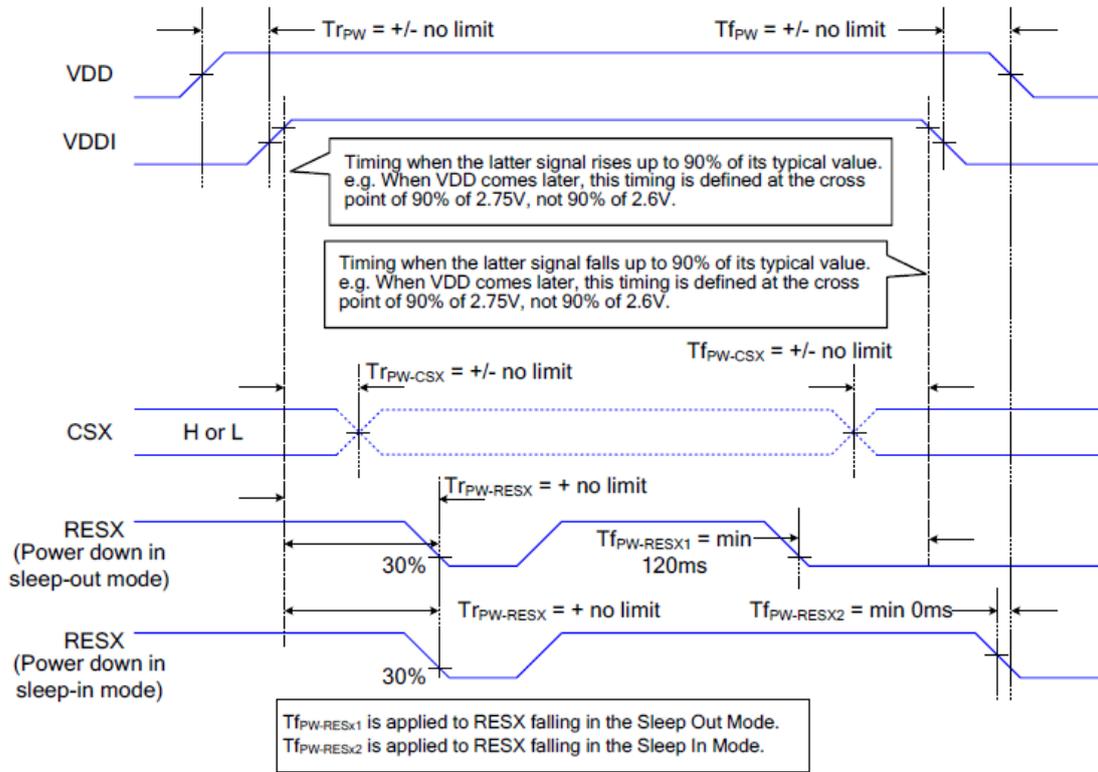
#### 3.1.3 Backlight driving conditions

Item	Symbol	Values			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V <sub>L</sub>	5.4	6.0	6.6	V	Note 1
Current for LED Backlight	I <sub>L</sub>	--	80	--	mA	
LED life time	--	20000	--	--	Hr	Note 2

**Note 1:** The LED Supply Voltage is defined by the number of LED at Ta=25°C and I<sub>L</sub> =80mA.

**Note 2:** The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and I<sub>L</sub> =80mA.

3.2 Power on/off sequence

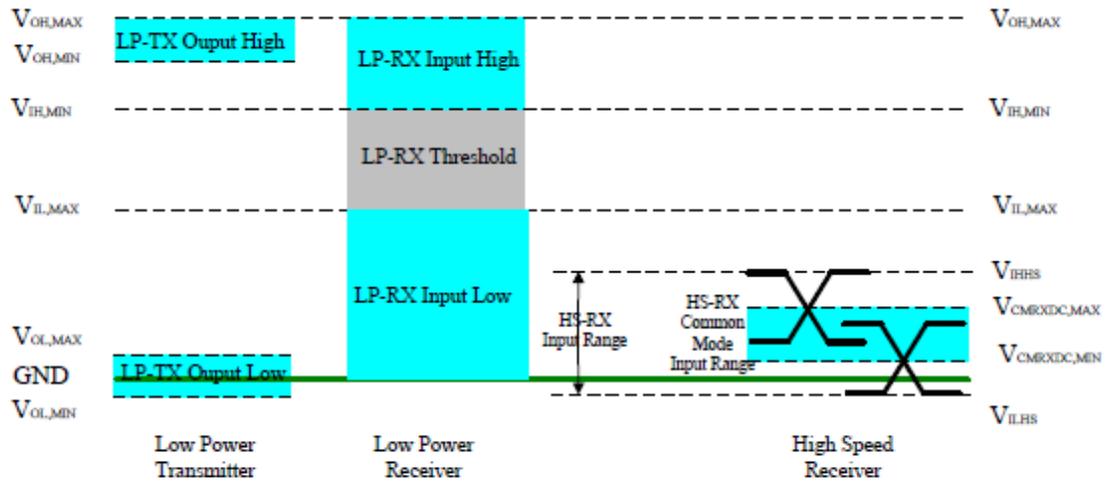


### 3.3 Input Signal Timing

#### 3.3.1 DC characteristics

Parameter	Symbol	Condition	Specification			Unit	Related Pins
			MIN.	TYP.	MAX.		
Power & Operation Voltage							
System Voltage	VDD	Operating voltage	2.5	2.8	3.6	V	
Interface Operation Voltage	VDDI	I/O Supply Voltage	1.65	1.8	3.3	V	
Gate Driver High Voltage	VGH		11.5		17	V	
Gate Driver Low Voltage	VGL		-7.6		-12	V	
Gate Driver Supply Voltage		VGH-VGL	-		30	V	
Input / Output							
Logic-High Input Voltage	VIH		0.7VDDI		VDDI	V	Note 1
Logic-Low Input Voltage	VIL		VSS		0.3VDDI	V	Note 1
Logic-High Output Voltage	VOH	IOH = -1.0mA	0.8VDDI		VDDI	V	Note 1
Differential Input High Threshold Voltage	VIT+			0	50	mV	MIPI_CLK MIPI_Data
Differential Input Low Threshold Voltage	VIT-		-50	0		mV	
Single-ended Receiver Input Operation Voltage Range	VIR		0.5		1.2	V	
Logic-Low Output Voltage	VOL	IOL = +1.0mA	VSS		0.2VDDI	V	Note 1
Logic-High Input Current	IIH	VIN = VDDI			1	uA	Note 1
Logic-Low Input Current	IIL	VIN = VSS	-1			uA	Note 1
Input Leakage Current	IIL	IOH = -1.0mA	-0.1		0.1	uA	Note 1
VCOM Voltage							
VCOM amplitude	VCOM			VSS		V	
Source Driver							
Gamma Reference Voltage(Positive)	VAP		4.4		6.4	V	
Gamma Reference Voltage(Negative)	VAN		-2.6		-4.6	V	
Source Output Settling Time	Tr	Below with 99% precision			10	us	Note 2

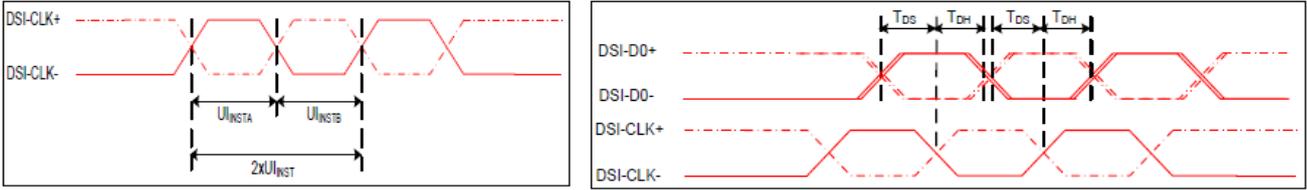
3.3.2 AC characteristics



$V_{DDI}=1.8, V_{DD}=2.8, A_{GND}=D_{GND}=0V, T_r=25^\circ C$

Parameter	Symbol	Specification			Unit
		MIN	TYP	MAX	
Operation Voltage for MIPI Receiver					
Low power mode operating voltage	$V_{LPH}$	1.1	1.2	1.3	V
MIPI Characteristics for High Speed Receiver					
Single-ended input low voltage	$V_{ILHS}$	-40	-	-	mV
Single-ended input high voltage	$V_{IHHS}$	-	-	460	mV
Common-mode voltage	$V_{CMRXDC}$	70	-	330	mV
Differential input impedance	$Z_{ID}$	80	100	125	ohm
MIPI Characteristics for Low Power Mode					
Pad signal voltage range	$V_I$	-50	-	1350	mV
Logic 0 input threshold	$V_{IL}$	0-	-	550	mV
Logic 1 input threshold	$V_{IH}$	880	-	1350	mV
Output low level	$V_{OL}$	-50	-	50	mV
Output high level	$V_{OH}$	1.1	1.2	1.3	V

3.3.2.1 High Speed Mode

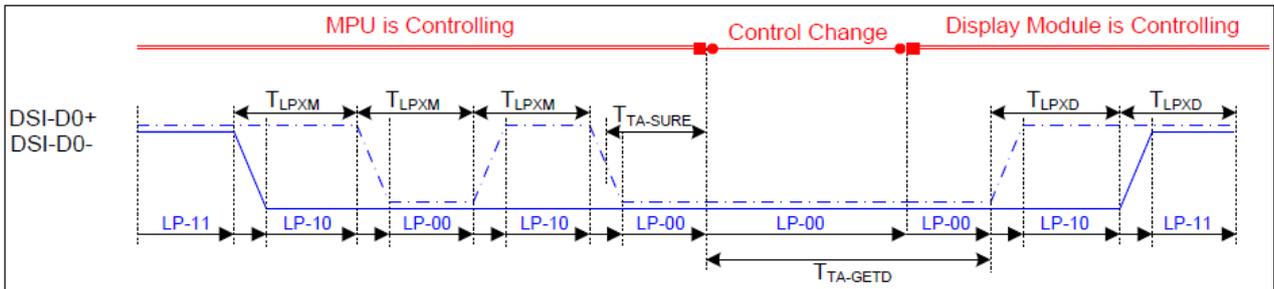


DSI clock channel timing

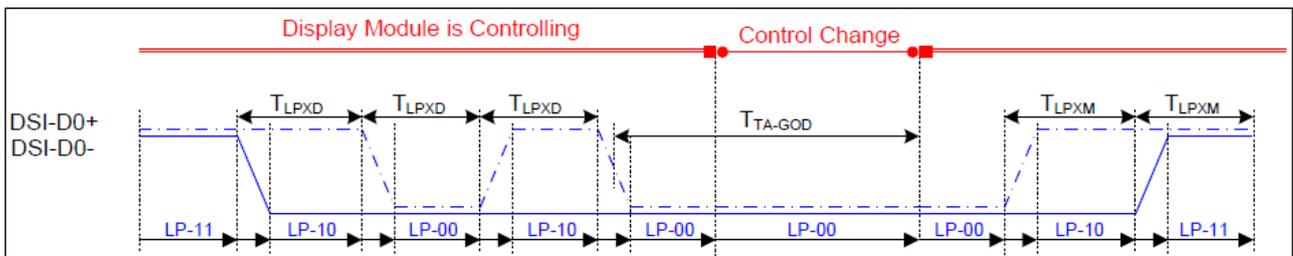
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	$2xUI_{INSTA}$	Double UI instantaneous	2.5	25	ns	
DSI-CLK+/-	$UI_{INSTA}$ $UI_{INSTB}$	UI instantaneous halves	1.25	12.5	ns	$UI = UI_{INSTA} = UI_{INSTB}$
DSI-Dn+/-	$t_{DS}$	Data to clock setup time	0.15	-	UI	
DSI-Dn+/-	$t_{DH}$	Data to clock hold time	0.15	-	UI	

Mipi Interface- High Speed Mode Timing Characteristics

3.3.2.2 Low Power Mode



Bus Turnaround (BTA) from display module to MPU Timing



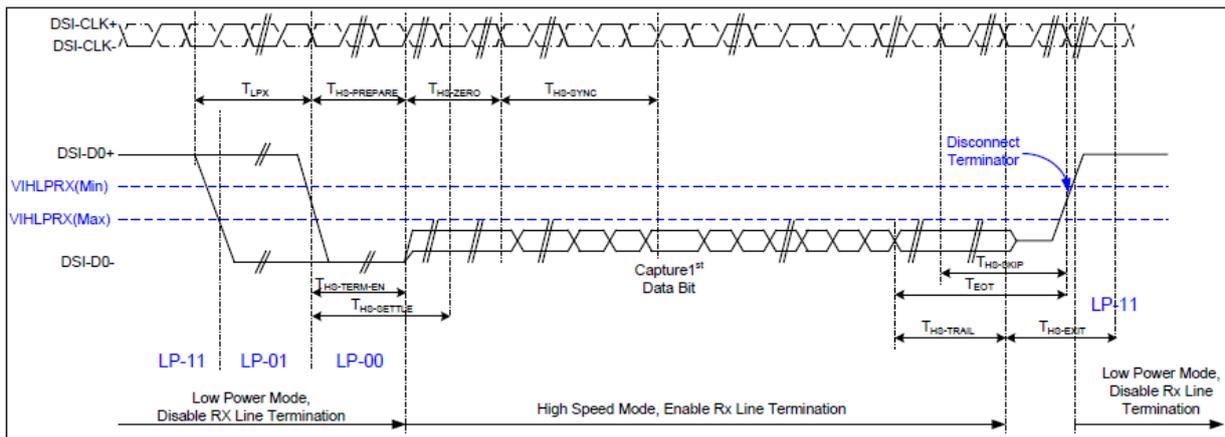
Bus Turnaround (BTA) from MPU to display module Timing

# ATMD210M1B (AZ DISPLAYS) TFT MODULE SPEC VER1.0

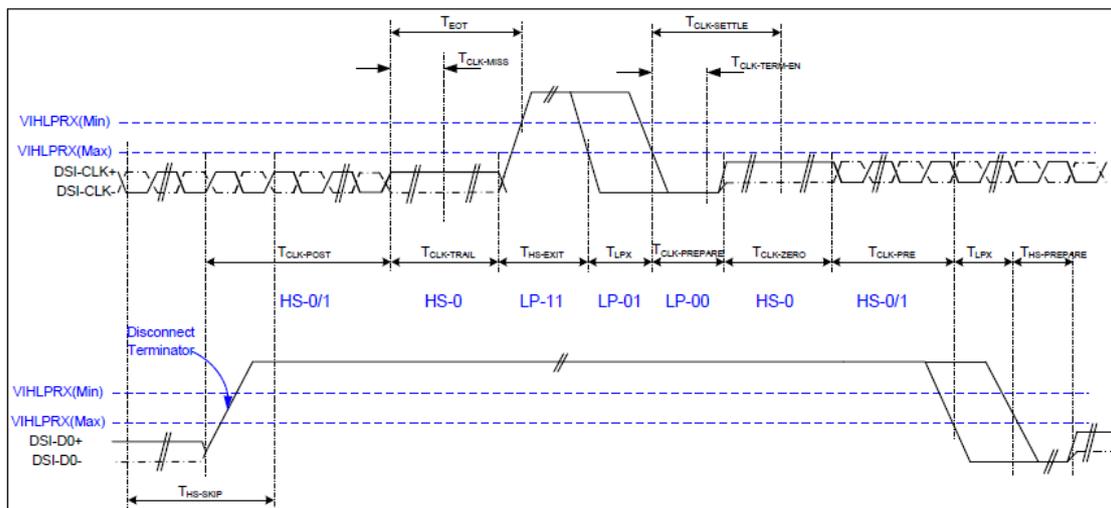
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-D0+/-	TLPXM	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Input
DSI-D0+/-	TLPXD	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Output
DSI-D0+/-	TTA-SURED	Time-out before the MPU start driving	$T_{LPXD}$	$2 \times T_{LPXD}$	ns	Output
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by display module	$5 \times T_{LPXD}$		ns	Input
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after turnaround request-MPU	$4 \times T_{LPXD}$		ns	Output

Mipi Interface Low Power Mode Timing Characteristics

### 3.3.2.3 DSI Bursts Mode



Data lanes-Low Power Mode to/from High Speed Mode Timing

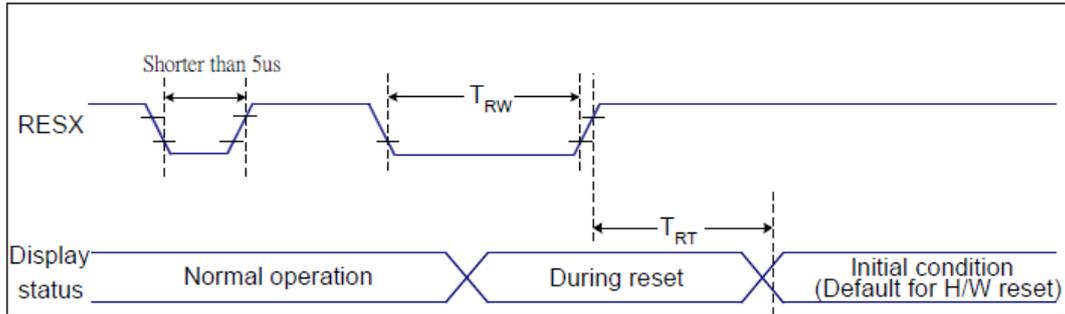


Clock lanes- High Speed Mode to/from Low Power Mode Timing

### 3.3.3 Input Timing Table

To be updated, or refer to IC datasheet

3.4 Reset Input Timing:



Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5) 120(Note 1, 6, 7)	ms ms

Notes:

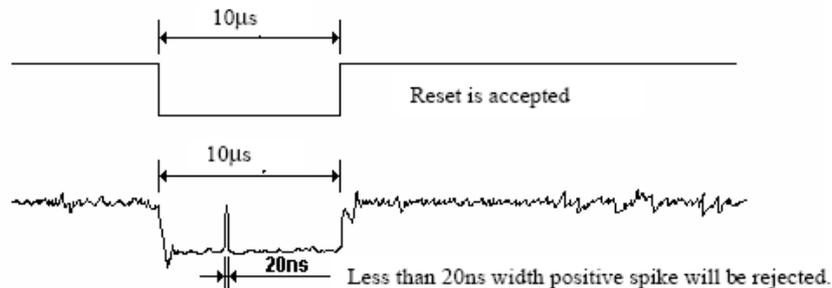
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

4.0 OPTICAL SPECIFICATIONS

Item	Symbol	Condition	Values			Unit	Remark
			Min.	Typ.	Max.		
Viewing Angle (CR ≥ 10)	$\theta_L$	$\Phi=180^\circ$ (9 O'CLOCK)	80	85	--	degree	Note 1
	$\theta_R$	$\Phi=0^\circ$ (3 O'CLOCK)	80	85	--		
	$\theta_T$	$\Phi=90^\circ$ (12 O'CLOCK)	80	85	--		
	$\theta_B$	$\Phi=270^\circ$ (6 O'CLOCK)	80	85	--		
Response Time	$T_{ON} + T_{OFF}$	Normal $\Theta=\Phi=0^\circ$	--	30	35	msec	Note 3
Contrast Ratio	CR		800	1000	--	--	Note 4
Color Chromaticity	$W_X$		0.26	0.31	0.36	--	Note 2
	$W_Y$		0.26	0.31	0.36	--	Note 5 Note 6
Luminance	L		500	600	--	cd/m <sup>2</sup>	Note 6
Luminance Uniformity	YU		75	80	--	%	Note 7

Test Conditions:

1. IL=80mA (Backlight current), the ambient temperature is 25°C.
2. The test systems refer to Note 2.

Note 1: Definition of viewing angle range

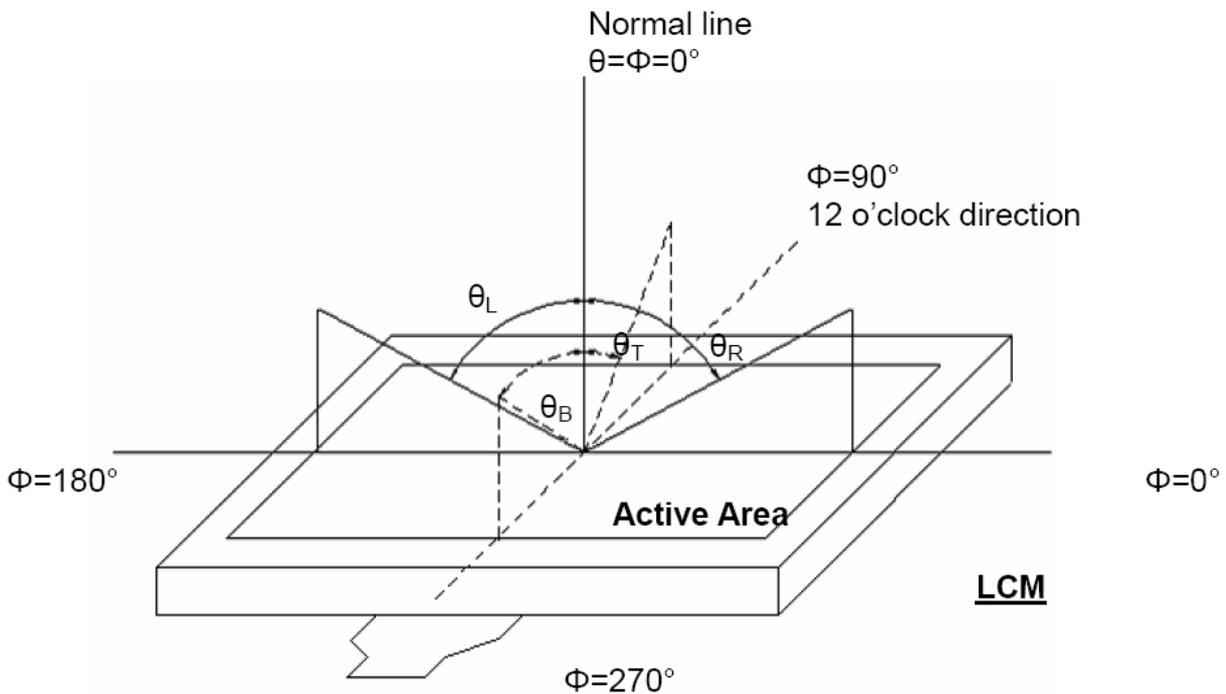


Figure 4.1 Definition of viewing angle.

**Note 2:** Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 30 minutes operation, the optical properties are measured at the center point of the LCD screen. (Response time is measured by Photo detector TOPCON)

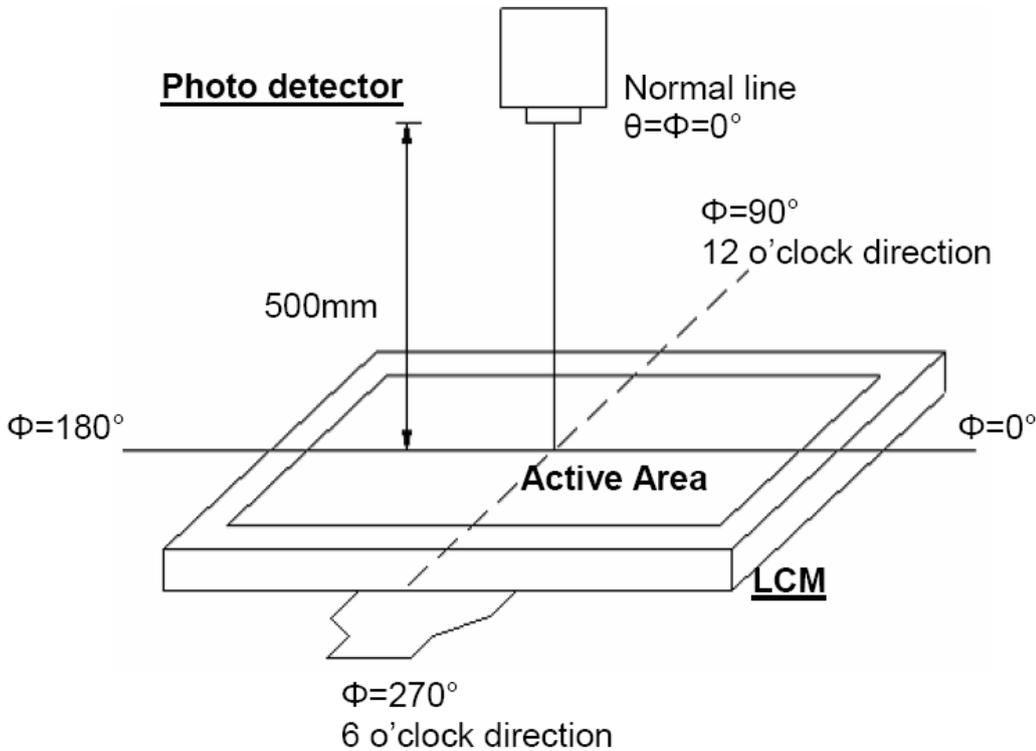


Figure 4.2 Optical measurement system setup

**Note 3:** Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time ( $T_{ON}$ ) is the time between photo detector output intensity changed from 90% to 10%. And fall time ( $T_{OFF}$ ) is the time between photo detector output intensity changed from 10% to 90%.

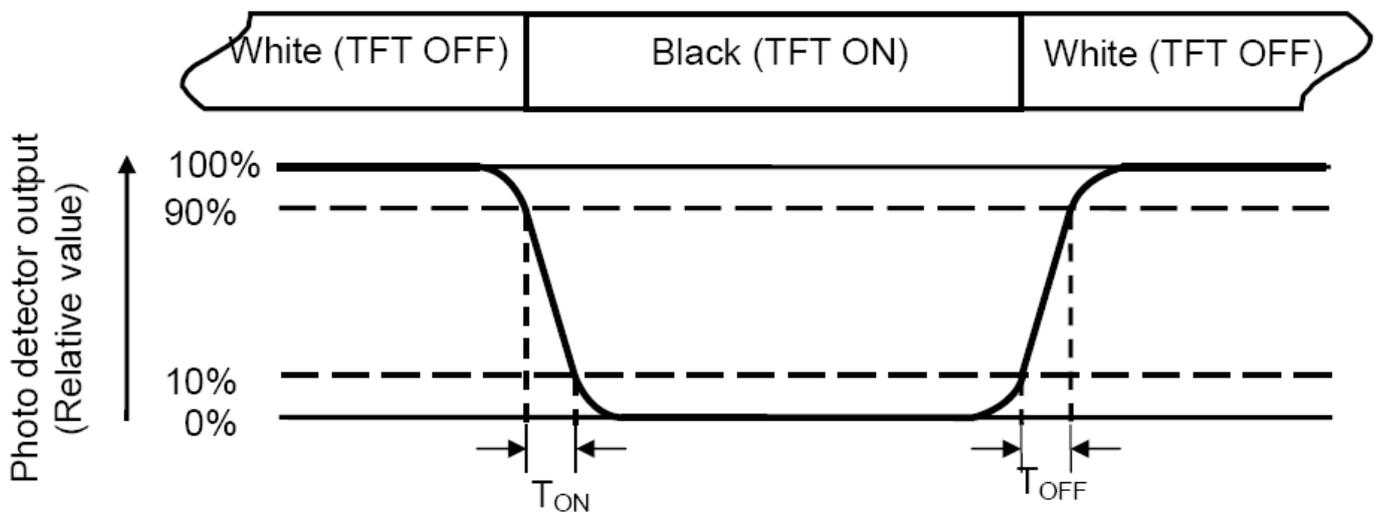


Figure 4.3 Definition of response.

**Note 4:** Definition of contrast ratio

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the "white" state}}{\text{Luminance measured when LCD on the "black" state}}$$

**Note 5:** Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

**Note 6:** All input terminals LCD panel must be ground while measuring the center area of the panel.

**Note 7:** Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer to Fig. 4.4 ).Every measuring point is placed at the center of each measuring area.

$$\text{Luminance Uniformity (Yu)} = \frac{B_{min}}{B_{max}}$$

L-----Active area length      W----- Active area width

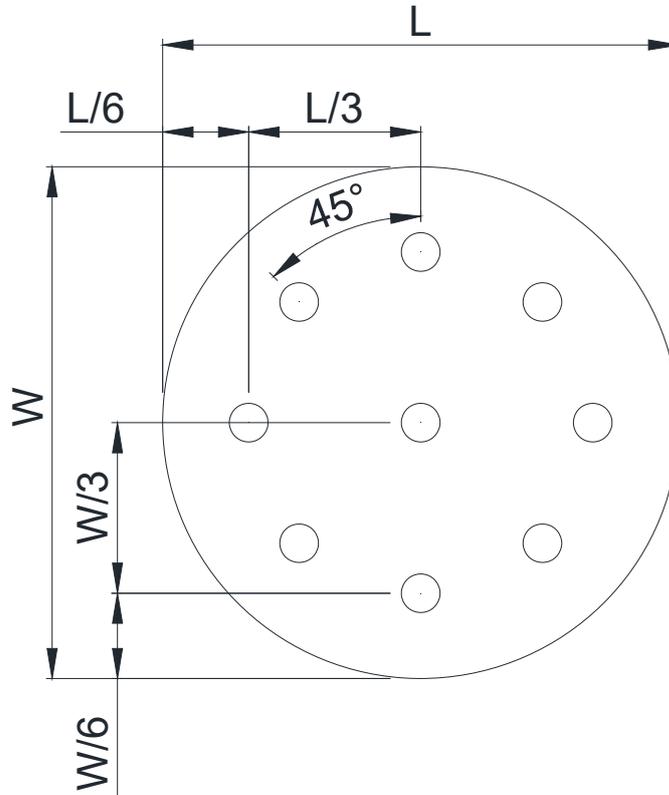


Figure 4.4 Definition of measuring points.

Bmax: The measured maximum luminance of all measurement position.

Bmin: The measured minimum luminance of all measurement position.

## 5. RELIABILITY TEST

Item	Test Condition Item	Remark
High temperature storage	Ta= 80 °C 96hrs	Note 1 Note 4
Low temperature storage	Ta=-30 °C 96hrs	Note 1 Note 4
High temperature operation	Ts= 70 °C 96hrs	Note 2 Note 4
Low temperature operation	Ts=-20 °C 96hrs	Note 1 Note 4
High temperature/High humidity operation	90% RH 60°C 96hrs	Note 4
Thermal Shock	-30°C/30 min ~ +80°C/30 min for a total 50 cycles, Start with cold temperature and end with high temperature.	Note 4
Vibration test	Freq:10~55~10Hz Amplitude:1.5mm 2 hours for each direction of X,Y,Z (6 hours for total)	
Mechanical shock	100G 6ms,±X, ±Y, ±Z 3 times for each direction	
Package vibration test	Random Vibration : 0.015G*G/Hz from 5-200HZ, -6dB/Octave from 200-500HZ 2 hours for each direction of X. Y. Z. (6 hours for total)	
Package drop test	Height:60 cm 1 corner, 3 edges, 6 surfaces	
Electro static discharge	± 2KV, Human Body Mode, 100pF/1500Ω	

**Note 1:** Ta is the ambient temperature of samples.

**Note 2:** Ts is the temperature of panel's surface.

**Note 3:** In the standard condition, there shall be no practical problem that may affect the display function. After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.

**Note 4:** Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.

## 6. PRECAUTION FOR USING LCM

1. When design the product with this LCD Module, make sure the viewing angle matches to its purpose of usage.
2. As LCD panel is made of glass substrate, Dropping the LCD module or banging it against hard objects may cause cracking or fragmentation. Especially at corners and edges.
3. Although the polarizer of this LCD Module has the anti-glare coating, always be careful not to scratch its surface. Use of a plastic cover is recommended to protect the surface of polarizer.
4. If the LCD module is stored at below specified temperature, the LC material may freeze and be deteriorated. If it is stored at above specified temperature, the molecular orientation of the LC material may change to Liquid state and it may not revert to its original state. Excessive temperature and humidity could cause polarizer peel off or bubble. Therefore, the LCD module should always be stored within specified temperature range.
5. Saliva or water droplets must be wiped off immediately as those may leave stains or cause color changes if remained for a long time. Water vapor will cause corrosion of ITO electrodes.
6. If the surface of LCD panel needs to be cleaned, wipe it swiftly with cotton or other soft cloth. If it is not still clean enough, blow a breath on the surface and wipe again.
7. The module should be driven according to the specified ratings to avoid malfunction and permanent damage. Applying DC voltage cause a rapid deterioration of LC material. Make sure to apply alternating waveform by continuous application of the M signal. Especially the power ON/OFF sequence should be kept to avoid latch-up of driver LSIs and DC charge up to LCD panel.
8. Mechanical Considerations
  - a) LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.
  - b) Do not tamper in any way with the tabs on the metal frame.
  - c) Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattern.
  - d) Do not touch the elastomer connector; especially insert a backlight panel (for example, EL).
  - e) When mounting a LCM makes sure that the PCB is not under any stress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
  - f) Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.
9. Static Electricity
  - a) Operator

Wear the electrostatics shielded clothes because human body may be statically charged if not ware shielded clothes. Never touch any of the conductive parts such as the LSI pads; the copper leads on the PCB and the interface terminals with any parts of the human body.
  - b) Equipment

There is a possibility that the static electricity is charged to the equipment, which has a function of peeling or friction action (ex: conveyer, soldering iron, working table). Earth the equipment through proper resistance (electrostatic earth:  $1 \times 10^8$  ohm).  
Only properly grounded soldering irons should be used.  
If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.  
The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
  - c) Floor

Floor is the important part to drain static electricity, which is generated by operators or equipment.  
There is a possibility that charged static electricity is not properly drained in case of insulating floor. Set the electrostatic earth (electrostatic earth:  $1 \times 10^8$  ohm).
  - d) Humidity

Proper humidity helps in reducing the chance of generating electrostatic charges. Humidity should be kept over 50%RH.
  - e) Transportation/storage

The storage materials also need to be anti-static treated because there is a possibility that the human body or storage materials such as containers may be statically charged by friction or peeling.  
The modules should be kept in antistatic bags or other containers resistant to static for storage.
  - f) Soldering

Solder only to the I/O terminals. Use only soldering irons with proper grounding and no leakage.  
Soldering temperature :  $280^{\circ} \text{C} \pm 10^{\circ} \text{C}$   
Soldering time: 3 to 4 sec.  
Use eutectic solder with resin flux fill.  
If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed afterwards.
  - g) Others

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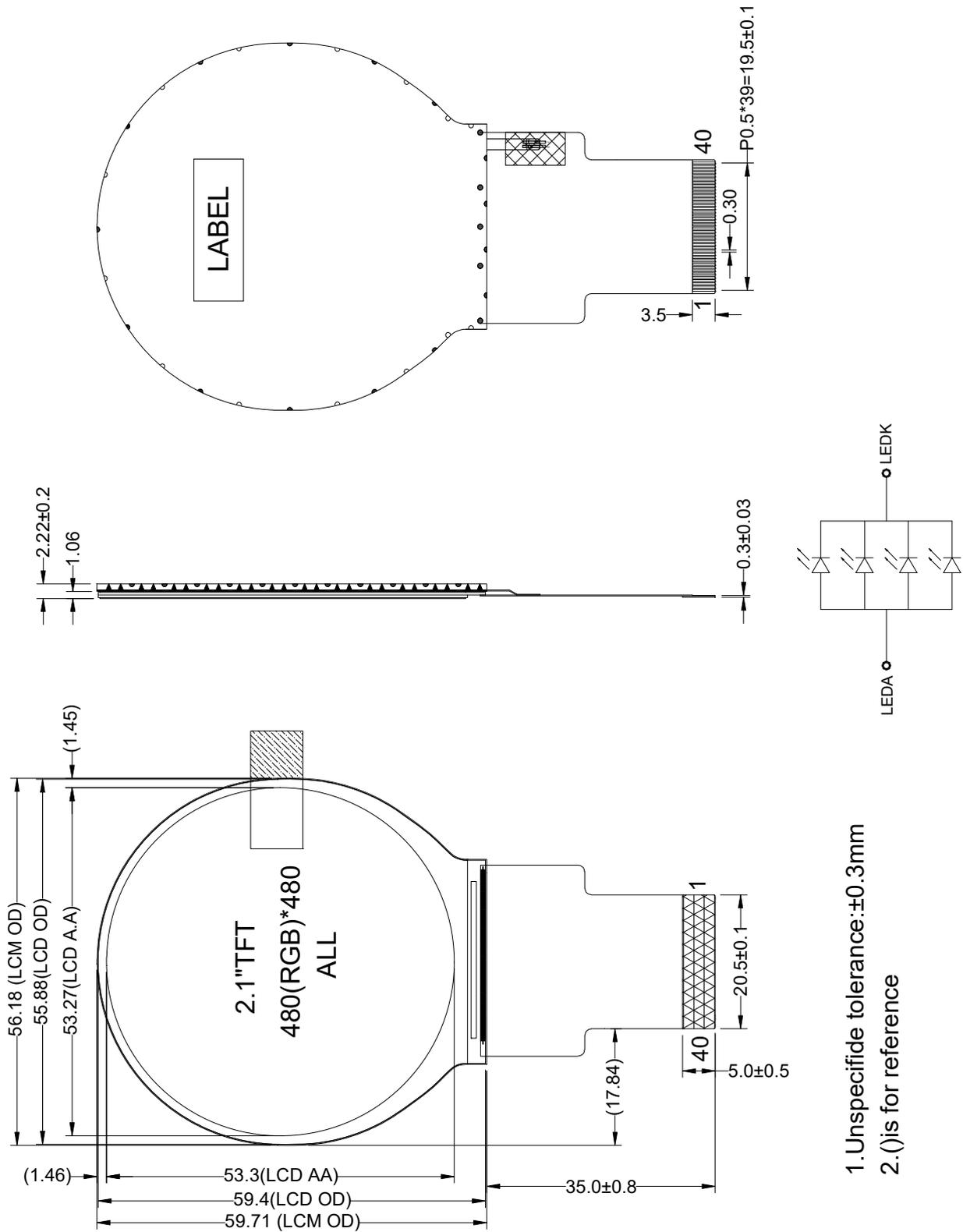
The laminator (protective film) is attached on the surface of LCD panel to prevent it from scratches or stains. It should be peeled off slowly using static eliminator.

Static eliminator should also be installed to the workbench to prevent LCD module from static charge.

### 10. Operation

- a) Driving voltage should be kept within specified range; excess voltage shortens display life.
  - b) Response time increases with decrease in temperature.
  - c) Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
  - d) Mechanical disturbance during operation (such as pressing on the viewing area) may cause the segments to appear "fractured".
11. If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. The toxicity is extremely low but caution should be exercised at all the time.
  12. Disassembling the LCD module can cause permanent damage and it should be strictly avoided.
  13. LCD retains the display pattern when it is applied for long time (Image retention). To prevent image retention, do not apply the fixed pattern for a long time. Image retention is not a deterioration of LCD. It will be removed after display pattern is changed.
  14. Do not use any materials, which emit gas from epoxy resin (hardener for amine) and silicone adhesive agent (dealcohol or deoxym) to prevent discoloration of polarizer due to gas.
  15. Avoid the exposure of the module to the direct sunlight or strong ultraviolet light for a long time. The brightness of LCD module may be affected by the routing of CCFL cables due to leakage to the chassis through coupling effect. The inverter circuit needs to be designed taking the level of leakage current into consideration. Thorough evaluation is needed for LCD module and inverter built into its host equipment to ensure specified brightness.

7. MECHANICAL DRAWING



- 1. Unspecifide tolerance:±0.3mm
- 2. ( )is for reference

**8. PACKAGE DRAWING**  
**T.B.D.**

**9. INSPECTION SPECIFICATION**

**1. SCOPE SPECIFICATIONS CONTAIN**

- 1.1 DISPLAY QUALITY EVALUATION
- 1.2 MECHANICS SPECIFICATION

**2. SAMPLING PLAN**

UNLESS THERE IS OTHER AGREEMENT, THE SAMPLING PLAN FOR INCOMING INSPECTION SHALL FOLLOW MIL-STD-105E.

- 2.1 LOT SIZE: QUANTITY PER SHIPMENT AS ONE LOT (DIFFERENT MODEL AS DIFFERENT LOT ).
- 2.2 SAMPLING TYPE: NORMAL INSPECTION, SINGLE SAMPLING.
- 2.3 SAMPLING LEVEL: LEVEL II.
- 2.4 AQL: ACCEPTABLE QUALITY LEVEL
  - MAJOR DEFECT: AQL=0.65
  - MINOR DEFECT: AQL=1.0

**3. PANEL INSPECTION CONDITION**

- 3.1 ENVIRONMENT:
  - ROOM TEMPERATURE: 25±5°C.
  - HUMIDITY: 65±5% RH.
  - ILLUMINATION: 300 ~ 700 LUX.
- 3.2 INSPECTION DISTANCE:
  - 35±5 CM
- 3.3 INSPECTION ANGLE:
  - THE VISION OF INSPECTOR SHOULD BE PERPENDICULAR TO THE SURFACE OF THE MODULE.
- 3.4 INSPECTION TIME:
  - PERCEPTIBILITY TEST TIME: 20 SECONDS MAX.

**4. DISPLAY QUALITY**

- 4.1 FUNCTION RELATED:
  - THE FUNCTION DEFECTS OF LINE DEFECT, ABNORMAL DISPLAY, AND NO DISPLAY ARE CONSIDERED MAJOR DEFECTS.
- 4.2 BRIGHT/DARK DOTS:

Defect Type	Specification	Major	Minor
Bright Dots	N ≤ 1		●
Dark Dots	N ≤ 2		●
Total Bright and Dark Dots	N ≤ 2		●

Note: 1:

The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot.  
 Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.  
 The bright dot defect must be visible through 2% ND filter  
 Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue pattern.

4.3 Pixel Definition:

R	G	B	R	G	B	R	G	B			Dot Defect
R	G	B	R	G	B	R	G	B			Adjacent Dot Defect
R	G	B	R	G	B	R	G	B			Cluster

Note 1:

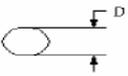
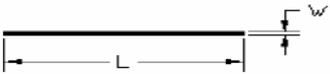
If pixel or partial sub-pixel defects exceed 50% of the affected pixel or sub-pixel area, it shall be considered as 1 defect.

Note 2:

There should be no distinct non-uniformity visible through 2% ND Filter within 2 sec inspection times.

## ATMD210M1B (AZ DISPLAYS) TFT MODULE SPEC VER1.0

### 4.4 Visual Inspection specifications:

<b>Defect Type</b>		<b>Specification Size</b>	<b>Count(N)</b>	<b>Major</b>	<b>Minor</b>		
Dot Shape (Particle · Scratch and Bubbles in display area) 		$D \leq 0.1\text{mm}$	Ignored		•		
		$0.1\text{mm} < D \leq 0.25\text{mm}$	$N \leq 3$				
		$D > 0.25\text{mm}$	$N=0$				
Newton Ring (Only for Touch panel)		$D \leq 70\text{mm}$	$N \leq 1$		•		
		$D > 70\text{mm}$	$N=0$				
TSP Fish Eyes (Only for Touch panel) (Bubble/Dent)		$0.1\text{mm} < D \leq 0.2\text{mm}$	$N \leq 2$		•		
		$0.2\text{mm} < D \leq 0.3\text{mm}$	$N \leq 1$				
		$0.3 < D \leq 0.4$	$N \leq 0$				
Line Shape (Particles · Scratch · Lint and Bubbles in display area) 		$W \leq 0.01\text{mm}$	Ignored		•		
		$0.01\text{mm} < W \leq 0.05\text{mm}$ and $L \leq 3\text{mm}$	$N \leq 2$				
		$W > 0.05\text{mm}$ or $L > 3\text{mm}$	$N=0$				
Bubble in cell (active area)		It should be found by eyes			•		
Bezel	Scratch	No harm			•		
	Dirt				•		
	Wrap				•		
	Sunken				•		
Label	No label	No			•		
	Inverted label				•		
	Broken				•		
	Dirt			Word can be read.		•	
	Not clear			No			•
	Word out of shape						•
	Mistake						•
	Position	Be attached on right position			•		
Screw	Not enough	No			•		
	Limp	No			•		

## ATMD210M1B (AZ DISPLAYS) TFT MODULE SPEC VER1.0

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Connector	Connection status	No bend on pins and damage		•
FPC/FFC	Broken	No		•

Note: Extraneous substance and scratch not affecting the display of image, for instance, extraneous substance under polarizer film but outside the display area, or scratch on metal bezel and backlight module or polarizer film outside the display area, shall not be considered as defective or non-conforming.